

COMPLETE SET OF PENDING CLAIMS

1. (Original) A method for removing a metallic contamination from a wafer container of the type used for holding wafers plated with metal, comprising the steps of:

spraying inside surfaces of the container with a solution of a liquid including a chelating agent;

rinsing the container; and

drying the container.

2. (Original) The method of claim 1 further including the step of spraying the inside surfaces of the container via spray nozzles oriented at different angles.

3. (Original) The method of claim 1 wherein the concentration of the chelating agent in the solution is 10-100 parts per million.

4. (Original) The method of claim 3 wherein the concentration of the chelating agent is 20-60 parts per million.

5. (Original) The method of claim 1 wherein the metal comprises copper.

6-9. (Cancelled)

10. (Currently Amended) The method of claim 6 1 wherein the solution comprises a chelating agent and de-ionized water.

11. (Original) The method of claim 1 further comprising the step of spraying the containers with a surfactant solution.

12. (Original) The method of claim 11 wherein the liquid includes the surfactant solution.

13. (Original) A method for removing a metal from a wafer container having inside and outside surfaces, comprising the steps of:

spraying the inside and outside surfaces of the container with a chelating agent solution comprising 1,2-Diaminocyclohexane-N,N,N',N'-tetraacetic acid monohydrate;

rinsing the container by spraying the inside and outside surfaces of the container with a rinsing solution including water; and

drying the container.

14. (Original) A method for removing a metal from a wafer container, comprising the steps of:

spraying inside surfaces of the container with a cleaning solution consisting essentially of water, a chelating agent, and a detergent or surfactant;

rinsing the container by spraying the inside surfaces with a rinsing solution including water; and
drying the container.

15. (Original) The method of claim 14 further including the step of spraying outside surfaces of the container with the cleaning solution and with the rinsing solution, via a plurality of spray nozzles oriented at different spray angles.

16. (New) A method for removing a metallic contamination from a wafer container of the type used for holding wafers plated with metal, comprising the steps of:
loading the container into a rotor;
spinning the rotor at a first speed;
spraying surfaces of the container spinning on the rotor with a solution of a liquid including a chelating agent;
rinsing the container; and
drying the container.

17. (New) The method of claim 16 further comprising the step of spinning the rotor at a second speed that is faster than the first speed during the drying step.

18. (New) The method of claim 16 wherein the concentration of the chelating agent in the solution is 20-60 parts per million.

19. (New) The method of claim 1 further comprising the step of irradiating the container with UV light to enhance the removal of the metallic contamination.

20. (New) A method for removing a metallic contamination from a wafer container of the type used for holding wafers plated with metal, comprising the steps of:

holding the container in a stationary position on a fixture;

spraying surfaces of the container with a solution of a liquid including a chelating agent;

rinsing the container; and

drying the container.